

Electronic Patent Application Fee Transmittal

Application Number:	10552046			
Filing Date:	09-Jan-2007			
Title of Invention:	Multi-chip ball grid array package and method of manufacture			
First Named Inventor/Applicant Name:	Fung Leng Chen			
Filer:	Carl Joseph Pellegrini/ruth swanson			
Attorney Docket Number:	Q74738			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				810